



XMOS Ltd.  
5th Floor East, Programme, 1 All Saints Street  
Bristol, BS1 2LZ, United Kingdom  
Tel: +44 117 927 6004, Web: www.xmos.com

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## **California Proposition 65 Position Statement**

California Proposition 65 known as the Safe Drinking Water and Toxic Enforcement Act of 1986 refers to the California legislation that was intended to protect California citizens and the State's drinking water sources from chemicals known to cause cancer, birth defects or other reproductive harm.

Consistent with our core values, XMOS strives to provide high quality, safe products to our customers. XMOS persistently works with our suppliers and customers to meet consumer product safety requirements applicable to our products, including California Proposition 65.

XMOS hereby confirms one of the chemicals listed by the Office of Environmental Health Hazard Assessment (OEHHA) of California Environmental Protection Agency is intentionally used in our IC semiconductor products. The chemical is Nickel. However, there is no risk in exposure of Nickel inside XMOS's products to the environment or human contact, more information is provided in the Appendix.

XMOS will continue to monitor California Proposition 65 regulations update for any addition of new chemicals going forward.

Sincerely,

A handwritten signature in blue ink, appearing to read 'Sunny Suen'.



Sunny Suen  
SVP Operations  
XMOS Ltd.

## **Appendix – Additional information:**

- 1) Nickel is used in the manufacturing of IC packaging of XMOS's semiconductor products.
  - For substrate-based package such as BGA/LGA, Nickel is used as base layer of circuit traces on substrate PCB. However, it is completely covered by a top layer of Gold, and then further covered by solder mask. This ensures the Nickel metal in the circuit traces is not exposed to the environment or human contact.
  - For QFP lead-frame type package, the lead frame is made of Copper-Nickel alloy (30+ to 1 ratio between Copper and Nickel by weight) with Tin plating covering this alloy completely. Therefore, there is no risk of Nickel metal release to the environment or exposure to human contact.
  - For QFN lead-frame type package, Nickel is not present, hence not applicable.
  
- 2) Minute amount of Carbon Black is added to the plastic molding of the IC package to make its body color black. However, since this usage of Carbon Black is in molded form (cannot be breathed in by humans) and not in powder form (can be breathed in by humans), hence this application is compliant with CA Prop65.
  
- 3) Tin used in plating of lead-frames for QFP and QFN packages has naturally existing trace amount of Lead (not intentionally added) of up to 2 micro-grams per IC device which present no risk to humans since it is trapped by the Tin. The amount is too minute to present any health hazard to humans and is within NSRL and MADL in CA Prop65.